

## **DAIKIN MALAYSIA GROUP SCHOLARSHIP PROGRAM**

### **Scholars (students) Eligibility:**

- a. Malaysian
- b. Full-time student
- c. Student pursuing a Bachelor's Degree
- d. Already gained acceptance into Malaysian Universities (IPTA/ IPTS). Preference will be given to students from IPTA.
- e. Possess good academic results:
  - i. **Students who will enroll into 1<sup>st</sup> year degree program**
    - SPM or equivalent – min **6As** + pass all subjects. Good results in Mathematics, English, and Bahasa Malaysia.
    - STPM or equivalent – min **2As** + pass all subjects
    - MUET – min **Band 4**
  - ii. **Students currently pursuing 1<sup>st</sup> year degree program**
    - SPM or equivalent – min **6As** + pass all subjects. Good results in Mathematics, English, and Bahasa Malaysia
    - STPM or equivalent – min **2As** + pass all subjects
    - MUET – min **Band 4**
    - Min GPA or CGPA **3.00**
- f. Actively participated in co-curriculum activities and displayed outstanding leadership qualities
- g. Strong communications skills
- h. Possess positive attitude
- i. Medically fit
- j. Have not received any other financial aid from any organization
- k. Scholars who are free from any future employment obligations
- l. Students who meet the above criteria (a to k) are welcome to apply. However, preference will be given to students from families with household income of RM5,000 per month or below.

### **Types of Eligible Courses**

Bachelor of Degree in:

- a. Engineering (preferably in Electrical & Electronics, Mechanical, Mechatronic, Manufacturing)
- b. IT
- c. Accounting
- d. Business / Management
- e. Sciences

### **Scholar's Obligations:**

- a. Serves a bond with company offering the scholarship for a minimum of duration sponsor.
- b. The bond will start immediately upon completion of degree course with the appointment letter given.
- c. Scholar will be required to work in the sponsor company or any subsidiary companies within Daikin Malaysia Group.
- d. Perform internship in the sponsor company or at any subsidiary within Daikin Malaysia Group during semester break.
- e. Scholar shall reimburse 100% of the scholarship fees should he/she resign from the company or is terminated during the period of the bond.

### **Application**

- a. Application form can be downloaded from <http://www.daikinmalaysia.com>
- b. Applicants must submit their application to [daikin.scholarship@daikin.com.my](mailto:daikin.scholarship@daikin.com.my) with all documents attached in PDF format.
- c. Applications are open for submission now and close on 30<sup>th</sup> September 2017.

### **Selection**

- a. Only shortlisted candidates will be contacted.
- b. The final selection will be based on interview results.

### **THE FOLLOWING APPLICATION WILL NOT BE PROCESSED:**

- a. Incomplete submission of documents.
- b. Scholars (students) who do not meet the criteria in para (1).
- c. Application received after the deadline.

### **Download Application Form as Below.**

- DAIKIN MALAYSIA GROUP SCHOLARSHIP PROGRAM (Excel).
- DAIKIN MALAYSIA GROUP SCHOLARSHIP PROGRAM (Pdf).

For any further enquiries, please email to [daikin.scholarship@daikin.com.my](mailto:daikin.scholarship@daikin.com.my).